

Problem 1 Chip Speed

Data

$$\rho_{\text{Cu}} := 1.724 \cdot 10^{-6} \cdot \text{ohm} \cdot \text{cm}$$

$$\rho_{\text{Al}} := 2.824 \cdot 10^{-6} \cdot \text{ohm} \cdot \text{cm}$$

$$n_{\text{SiO}_2} := 1.$$

$$\epsilon_o := 8.854 \cdot 10^{-12} \cdot \frac{\text{F}}{\text{m}}$$

$$\epsilon_{\text{SiO}_2} := n_{\text{SiO}_2}^2$$

$$\text{Thickness} := 0.25 \cdot \mu\text{m}$$

$$\text{Gap} := 3 \cdot \text{Th}$$

$$\text{Height} := 3 \cdot \text{Thickness}$$

$$\text{Length} := 2000 \cdot \text{Thickness}$$

$$\text{Area}_{\text{wire}} := \text{Height} \cdot \text{Thickness}$$

$$\text{Area}_{\text{plate}} := \text{Length} \cdot \text{Height}$$

$$R := \rho_{\text{Al}} \cdot \frac{\text{Length}}{\text{Area}_{\text{wire}}}$$

$$C := \epsilon_{\text{SiO}_2} \cdot \epsilon_o \cdot \frac{2 \cdot \text{Area}_{\text{plate}}}{\text{Gap}}$$

$$\text{Chip_Speed} := (R \cdot C)^{-1}$$

$$\text{Chip_Speed} = 0.624 \text{ GHz}$$

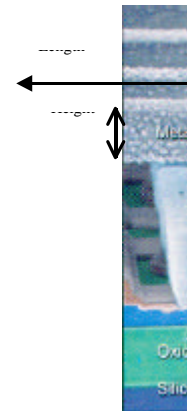
Al wiring

$$R := \rho_{\text{Cu}} \cdot \frac{\text{Length}}{\text{Area}_{\text{wire}}}$$

$$\text{Chip_Speed} := (R \cdot C)^{-1}$$

$$\text{Chip_Speed} = 1.023 \text{ GHz}$$

Cu wiring



Problem 2 A Crystal Growth via BL MT

Silicon Properties

$$\frac{1}{6} \cdot \text{Hz} = 10 \cdot \frac{1}{\text{min}} = \text{rpm}$$

$$\omega := 2 \cdot \pi \cdot \frac{1}{6} \cdot \text{Hz}$$

$$D_{\text{boule}} := 30 \cdot \text{cm}$$

$$T := T_{\text{eq}} - 2 \cdot \text{K}$$

$$\rho := 2.33 \cdot \frac{\text{gm}}{\text{cm}^3}$$

$$u := 0.1 \cdot \text{poise}$$

$$M_w := 28 \cdot \frac{\text{gm}}{\text{mole}}$$

$$T_{\text{eq}} := 1685 \cdot \text{K}$$

$$v := \frac{\mu}{\rho}$$

$$v = 4.292 \times 10^{-6} \cdot \frac{\text{m}^2}{\text{s}}$$

$$k := 1.48 \cdot \frac{\text{watt}}{\text{cm} \cdot \text{K}}$$

$$D := 8 \cdot 10^{-4} \cdot \frac{\text{cm}^2}{\text{s}}$$

$$\Delta H_f := 50550 \cdot \frac{\text{joule}}{\text{mole}}$$

(- \Delta H_f \cdot T \cdot T)

$$S(T) := \exp\left(\frac{-\Delta H_f}{R_g \cdot T_{eq}} \cdot \frac{T - T_{eq}}{T}\right) \quad S(T) = 1.004$$

$$\text{Flux}_C(S) := 0.62 \cdot D^{\frac{2}{3}} \cdot C_{eq} \cdot v^{\frac{-1}{6}} \cdot \omega^{\frac{1}{2}} \cdot (S - 1)$$

$$\text{Flux}_C(S(T)) = 0.033 \frac{\text{mol}}{\text{m}^2 \text{s}}$$

$$\text{GrowthRate}_C(S) := \frac{\text{Flux}_C(S) \cdot M_w}{\rho}$$

$$\text{GrowthRate}_C(S(T)) = 3.982 \times 10^{-4} \frac{\text{mm}}{\text{s}}$$



Problem 2 B Crystal Growth via BL HT
uses Data from 2A

$$h := 0.62 \cdot \left[\left(\frac{\omega}{v} \right)^{\left(\frac{1}{2} \right)} \cdot \left(\frac{v}{\alpha} \right)^{\left(\frac{1}{3} \right)} \cdot k \right]$$

$$\alpha := \frac{k}{\rho \cdot C_p}$$

$$\text{Flux}_H(T) := \frac{h \cdot (T_{eq} - T)}{\Delta H_f}$$

$$T = 1.683 \times 10^3 \text{ K}$$

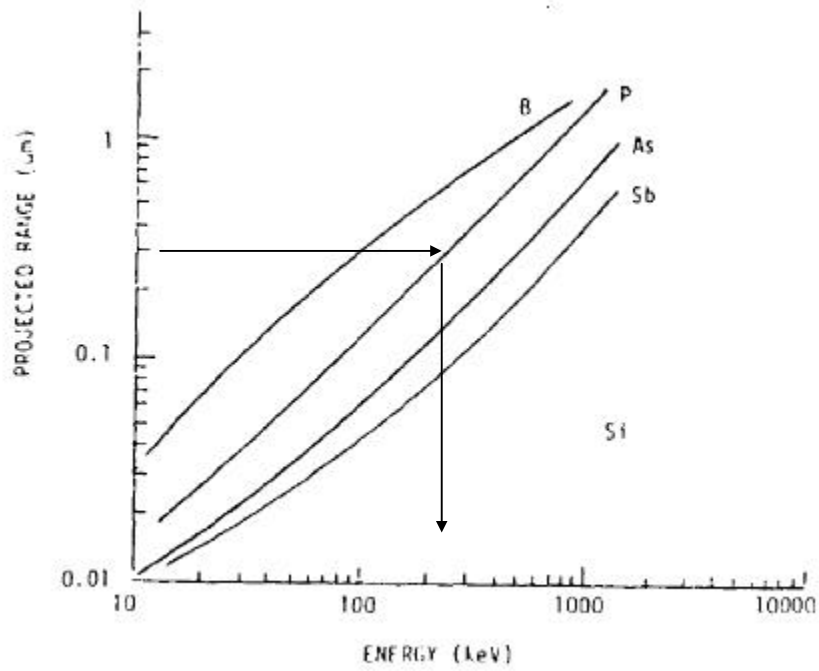
$$\text{Flux}_H(T) = 0.652 \frac{\text{mol}}{\text{m}^2 \text{s}}$$

$$\text{GrowthRate}_H(T) := \frac{\text{Flux}_H(T) \cdot M_w}{\rho}$$

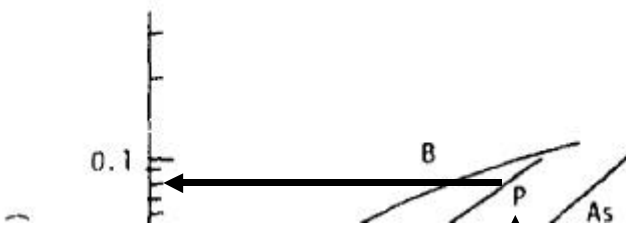
$$\text{GrowthRate}_H(T) = 7.83 \times 10^{-3} \frac{\text{mm}}{\text{s}}$$

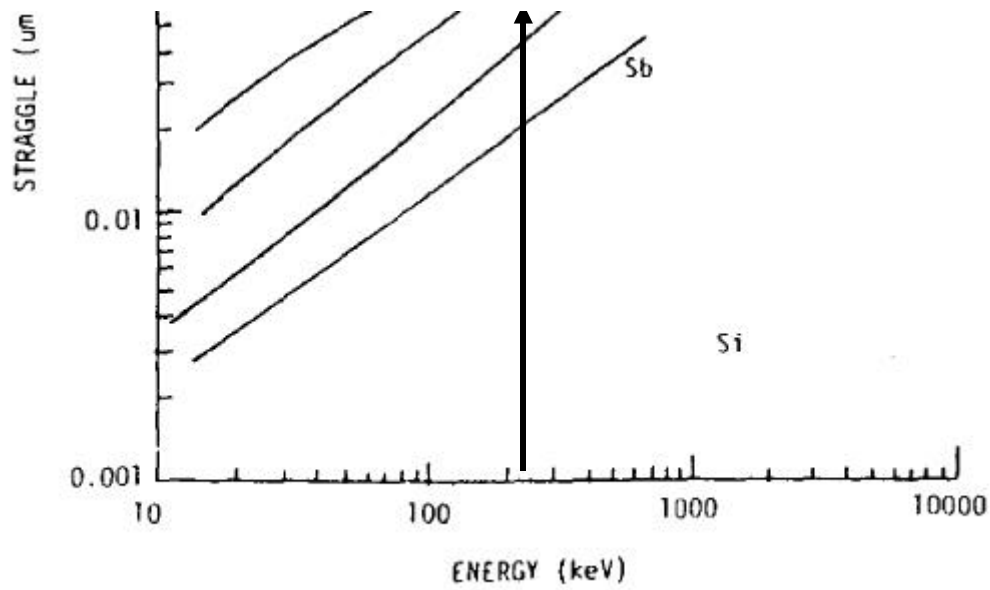
BL-MT gives the slower growth rate,
thus MT is rate determining.

Problem 3 Implantation



A) Implantation Energy from figure is 250 keV





Standard Deviation of Projected Range $\sigma_x = 0.08 \mu\text{m}$

$$\frac{0.08 \cdot \mu\text{m}}{0.3 \cdot \mu\text{m}} = 0.267$$

$\sigma_x := 0.08 \cdot \mu\text{m}$

taken from figure above

$D_{\text{wafer}} := 30 \cdot \text{cm}$

Silicon Data

$$N_{\text{Av}} := 6.023 \cdot 10^{23}$$

$$\rho := 2.33 \cdot \frac{\text{gm}}{\text{cm}^3}$$

$$M_w := 28 \cdot \frac{\text{gm}}{\text{mole}}$$

$$C_{\text{eq}} := \frac{\rho \cdot N_{\text{Av}}}{M_w}$$

$$C_{\text{eq}} = 5.012 \times 10^{22}$$

Dopant Dose Calculation

$$N_{\text{max}} := 0.00001 \cdot C_{\text{eq}}$$

$$N_{\text{max}} = \frac{N_{\text{dose}}}{\sqrt{2\pi} \cdot \sigma_x}$$

$$N_{\text{max}} = 5.012 \times 10^{17} \frac{1}{\text{cm}^3} \quad \# \text{ atoms/cm}^3$$

$$N_{\text{dose}}(N_{\text{max}}, \sigma_x) := N_{\text{max}} \cdot (\sqrt{2\pi} \cdot \sigma_x)$$

$$N_{\text{dose}}(N_{\text{max}}, \sigma_x) = 1.005 \times 10^{13} \frac{1}{\text{cm}^2}$$

$$Q_{\text{dose}}(N_{\text{max}}, \sigma_x) := N_{\text{dose}}(N_{\text{max}}, \sigma_x) \cdot (1.602 \cdot 10^{-19} \cdot \text{Coul}) \cdot \left(\frac{\pi \cdot D_{\text{wafer}}^2}{4} \right)$$

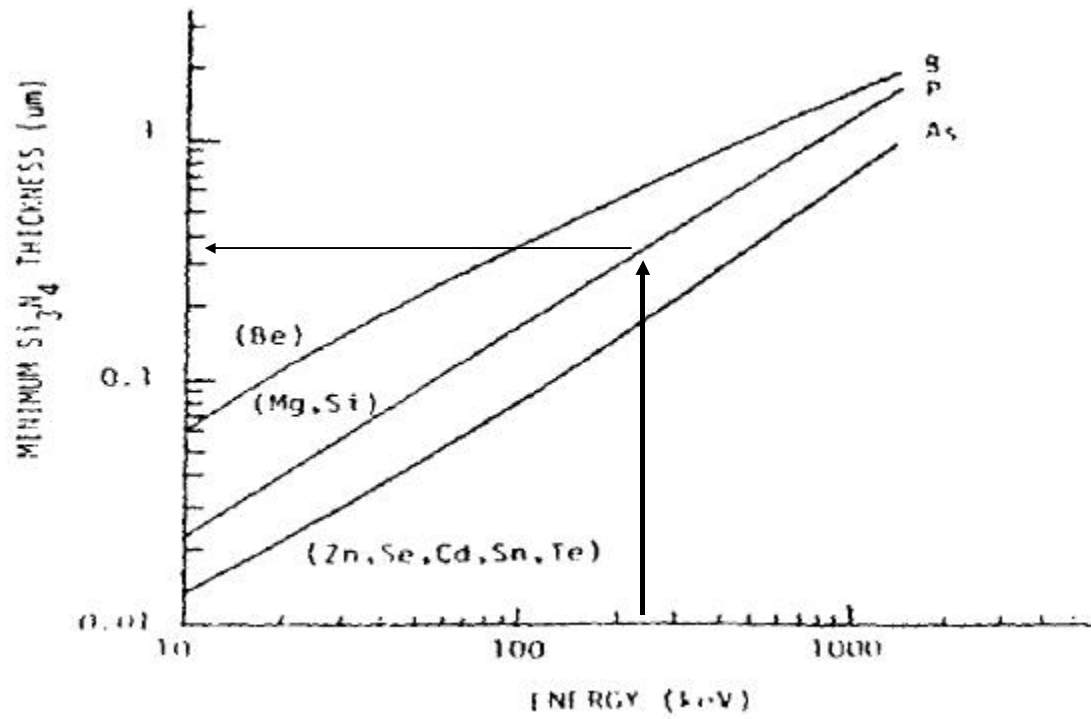
$$Q_{\text{dose}}(N_{\text{max}}, \sigma_x) = Q_{\text{dose}}(N_{\text{max}}, \sigma_x) \cdot (1.002 \cdot 10^{-10} \text{ cm}^2) \cdot (4 \cdot 10^{21} \text{ water})$$

$$Q_{\text{dose}}(N_{\text{max}}, \sigma_x) = 1.138 \times 10^{-3} \text{ A}\cdot\text{s}$$

Notice this is a short time

Remember the Video where the wafers are put into a speed carriage and pass in and out of the implantation chamber for many very short periods

3C) Si₃N₄ Mask Layer Growth



Minimum Si₃N₄ thickness = 0.37 μm



$$\rho_{\text{Si}} := 2.33 \cdot \frac{\text{gm}}{\text{cm}^3} \quad \rho_{\text{Si}_3\text{N}_4} := 3.44 \cdot \frac{\text{gm}}{\text{cm}^3}$$

$$\text{Mw}_{\text{Si}} := 28.08 \cdot \frac{\text{gm}}{\text{mole}} \quad \text{Mw}_{\text{Si}_3\text{N}_4} := 140.28 \cdot \frac{\text{gm}}{\text{mole}} \quad k_o := 1.2 \cdot 10^5 \cdot \frac{\text{cm}}{\text{s}} \quad E_A :=$$

$$H_{\text{fSi}} := 0 \cdot \frac{\text{cal}}{\text{mole}} \quad G_{\text{fSi}} := 0 \cdot \frac{\text{cal}}{\text{mole}} \quad S_{\text{Si}} := 4.5 \cdot \frac{\text{cal}}{\text{mole} \cdot \text{K}} \quad C_{\text{pSi}} := 4.78 \cdot \frac{\text{cal}}{\text{mole} \cdot \text{K}}$$

$$H_{\text{fSi}_3\text{N}_4} := -179300 \cdot \frac{\text{cal}}{\text{mole}} \quad G_{\text{fSi}_3\text{N}_4} := -154700 \cdot \frac{\text{cal}}{\text{mole}} \quad S_{\text{Si}_3\text{N}_4} := 22.4 \cdot \frac{\text{cal}}{\text{mole} \cdot \text{K}} \quad C_{\text{pSi}_3\text{N}_4} := 23.84 \cdot \frac{\text{cal}}{\text{mole} \cdot \text{K}}$$

$$H_{\text{fN}_2} := 0 \cdot \frac{\text{cal}}{\text{mole}} \quad G_{\text{fN}_2} := 0 \cdot \frac{\text{cal}}{\text{mole}} \quad S_{\text{N}_2} := 45.77 \cdot \frac{\text{cal}}{\text{mole} \cdot \text{K}} \quad C_{\text{pN}_2} := 6.961 \cdot \frac{\text{cal}}{\text{mole} \cdot \text{K}}$$

$$\Delta H_{\text{rxn}}(T) := \left[\frac{1}{2} \cdot H_{\text{fSi}_3\text{N}_4} - \left(\frac{3}{2} \cdot H_{\text{fSi}} + H_{\text{fN}_2} \right) \right] \dots$$

$$+ \left[\frac{1}{2} \cdot C_{\text{pSi}_3\text{N}_4} - \left(\frac{3}{2} \cdot C_{\text{pSi}} + C_{\text{pN}_2} \right) \right] \cdot (T - 298.15 \cdot \text{K})$$

$$\Delta H_{\text{rxn}}(298.15 \cdot \text{K}) = -8.96$$

$$\Delta G_{\text{rxn}}(T) := \Delta H_{\text{rxn}}(T) - T \cdot \left[\frac{1}{2} \cdot S_{\text{Si}_3\text{N}_4} - \left(\frac{3}{2} \cdot S_{\text{Si}} + S_{\text{N}_2} \right) \right]$$

$$\Delta G_{\text{rxn}}(298 \cdot \text{K}) = -7.73$$

$$K(T) := \exp\left(\frac{-\Delta G_{\text{rxn}}(T)}{R_g \cdot T}\right) \quad P_{\text{N}_2\text{eq}}(T) := \frac{P}{K(T)}$$

$$\text{Flux} = \frac{\rho_{\text{Si}_3\text{N}_4}}{\text{Mw}_{\text{Si}_3\text{N}_4}} \cdot \text{Area} \cdot \frac{dy}{dt} = \frac{\text{Rate}}{\text{Area}} = (2) \cdot k_o \cdot \exp\left(\frac{-E_A}{R_g \cdot T}\right) \cdot (C_{\text{N}_2} - C_{\text{N}_2\text{eq}}) \quad \text{Film Growth Equation}$$

$$C_{\text{N}_2} := \frac{P}{R_g \cdot T} \quad C_{\text{N}_2} = 1.111 \times 10^{-3} \frac{\text{mole}}{\text{m}^3}$$

$$C_{\text{N}_2\text{eq}}(T) := \frac{P_{\text{N}_2\text{eq}}(T)}{R_g \cdot T} \quad C_{\text{N}_2\text{eq}}(T) = 7.571 \times 10^{-13} \frac{\text{mol}}{\text{m}^3} \quad P_{\text{N}_2\text{eq}}(T) = 6.814 \times 10^{-14} \text{ atm}$$

Integrate Flux equation

$$y(t, T) := \frac{\text{Mw}_{\text{Si}_3\text{N}_4}}{\rho_{\text{Si}_3\text{N}_4}} \cdot \left[(2) \cdot k_o \cdot \exp\left(\frac{-E_A}{R_g \cdot T}\right) \cdot (C_{\text{N}_2} - C_{\text{N}_2\text{eq}}(T)) \right] \cdot t$$

Rearrange

$$t(T) := \frac{0.37 \cdot \mu\text{m}}{\frac{M_{\text{Si}_3\text{N}_4}}{\rho_{\text{Si}_3\text{N}_4}} \cdot \left[(2) \cdot k_o \cdot \exp\left(\frac{-E_A}{R_g \cdot T}\right) \cdot (C_{\text{N}_2} - C_{\text{N}_2\text{eq}}(T)) \right]}$$

$$t(T) = 2.187 \text{ min}$$

